Compliant with IEC 62474/ D9.00

Compliant to IEC 61249-2-21:2003

MICROCHIP Semiconductor Device Type: H4A 004 VDFN 3.2x2.5x0.9mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials				J-STD-609A Product Marking and/or Pkg. Labeling
Semiconductor Device Type:	H4A	004 VDFN 3.2x2.5x0.9mm NiPdAu "Contained In"	% Total	1				Т		e3
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm	9.08	(mg) Total	Mold Compound	% ot Total Weight	46.57
Silica, vitreous (or fused)	60676-86-0	Mold Compound	39.585	7.719	395.845		Silica, vitreous (or fused)	60676-86-0	85.00	
Epoxy Resin	Trade Secret	Mold Compound	3.958	0.772	39,585		Epoxy Resin	Trade Secret	8.50	
Phenolic Resin	Trade Secret	Mold Compound	1.630	0.318	16,300		Phenolic Resin	Trade Secret	3.50	
Silica, vitreous (or fused)	7631-86-9	Mold Compound	1.257	0.245	12,574		Silica, vitreous (or fused)	7631-86-9	2.70	
Carbon Black	1333-86-4	Mold Compound	0.140	0.027	1,397		Carbon Black	1333-86-4	0.30	1
Copper	7440-50-8	Lead Frame	45.132	8.801	451,324		Carbon Black	Total	100.00	1
Silver	7440-22-4	Lead Frame	0.883	0.172	8,826	9.03	(mg) Total	Lead Frame	% of Total Weight	46.33
Tin	7440-31-5	Lead Frame	0.116	0.023	1,158		Copper	7440-50-8	97.42	
Chromium	7440-47-3	Lead Frame	0.116	0.023	1,158		Silver	7440-22-4	1.91	1
Zinc	7440-66-6	Lead Frame	0.083	0.016	834		Tin	7440-31-5	0.25	
Silica Fused	60676-86-0	Die Attach1	0.388	0.076	3,879		Chromium	7440-47-3	0.25	
Epoxy Resin	120206-26-0	Die Attach1	0.115	0.022	1,148		Zinc	7440-66-6	0.18	_
Poly(Bisphenol A-co-epichlorohydrin)	25068-38-6	Die Attach1	0.087	0.017	874			Total	100.00	
Silver	7440-22-4	Die Attach2	0.367	0.071	3,666	0.12	(mg) Total	Die Attach1	% of Total Weight	0.59
Acrylic Resin	Trade secret	Die Attach2	0.103	0.020	1,034		Silica Fused	60676-86-0	65.74	
Doped Silicon	7440-21-3	Chip (Die)1	2.590	0.505	25,900		Epoxy Resin	120206-26-0	19.45	
Doped Silicon	7440-21-3	Chip (Die)2	1.580	0.308	15,800		Poly(Bisphenol A-co-	25068-38-6	14.81	
Doped Gold	7440-57-5	Wire Bond1	0.360	0.070	3,600		epichlorohydrin)	Total	100.00	_
Doped Gold Doped Gold	7440-57-5	Wire Bond1 Wire Bond2	0.360	0.070	1,500	0.09	() T-1-1	Die Attach2	% of Total Weight	
Nickel	7440-02-0		1.224	0.029	12,240	0.09	(mg) Total Silver	7440-22-4	78.00	0.47
Palladium	7440-02-0	Plating on external leads (pins) Plating on external leads (pins)	0.068	0.239	680					4
Gold	7440-05-5	Plating on external leads (pins)	0.068	0.013	680		Acrylic Resin	Trade secret Total	22.00	_
Gold	7440-37-3			19.500	1,000,000	0.54	T-1-1()			
		TOTALS g Total Mass	5: 100.000	19.500	1,000,000	0.51	Total (mg) Doped Silicon	Chip (Die)1 7440-21-3	% of Total Weight 100.00	2.59
/EC (End-of-Life Vehicles (ELV) without exemption (zero)		, , ,	ine 2011) and 2015	5/863/EU (31 Ma	rch 2015) and	0.31	Total (mg)	Total Chip (Die)2	100.00 % of Total Weight	
3/EC (End-of-Life Vehicles (ELV) without exemption (zero) inance with the above EU Directives has been verified via intern emical substance is absent from the list above, the chemical subrated's knowledge and belief as of the date of this document,	al design controls, substance is NOT and there is no credible	upplier declarations, and /or analytical test data.	the best of Micro	chip Technolog	, <u> </u>	0.31		Total	100.00	
3/EC (End-of-Life Vehicles (ELV) without exemption (zero) iance with the above EU Directives has been verified via intern emical substance is absent from the list above, the chemical su orated's knowledge and belief as of the date of this document, the threshold of regulatory concern for any regulatory scheme ag compounds used by Microchip meet the UL94 V0 flammabili	al design controls, substance is NOT an there is no credible world-wide.	upplier declarations, and /or analytical test data. Intentional ingredient in the semiconductor device and, to reason to believe that the unavoidable impurity concentra	the best of Micro	chip Technolog cal substance, i	, <u> </u>	0.31	Total (mg)	Total Chip (Die)2	100.00 % of Total Weight	1.58
3/EC (End-of-Life Vehicles (ELV) without exemption (zero) iance with the above EU Directives has been verified via intern smical substance is absent from the list above, the chemical substance is absent from the list above, the chemical substance is and belief as of the date of this document, the threshold of regulatory concern for any regulatory scheme g compounds used by Microchip meet the UL94 V0 flammabili al.com/global/eng/pages/offerings/industries/chemicals/plastic	al design controls, substance is NOT an there is no credible world-wide. ty standard for plasts/	upplier declarations, and /or analytical test data. ntentional ingredient in the semiconductor device and, to reason to believe that the unavoidable impurity concentra ics. You can access the UL iQTM family of databases to ol	the best of Micro ation of the chemi btain a test report	chip Technolog cal substance, i	y f any, is not		Total (mg) Doped Silicon	Total Chip (Die)2 7440-21-3 Total	100.00 % of Total Weight 100.00	1.58
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3/EC (End-of-Life Vehicles (ELV) without exemption (zero) iance with the above EU Directives has been verified via intern emical substance is absent from the list above, the chemical su orated's knowledge and belief as of the date of this document, the threshold of regulatory concern for any regulatory scheme ag compounds used by Microchip meet the UL94 V0 flammabilial.com/global/eng/pages/offerings/industries/chemicals/plastic otective "tubes" in which the specific product is shipped are now may be made from PVC plastic. The production of the programmaterials is true and correct to the best of its knowled curacy of data in this form because it has been compiled base ted from disclosure as trade secrets and some information may average weight of anticip	al design controls, substance is NOT an there is no credible world-wide. ty standard for plast s/ nade from polyvinyl orm concerning subside and belief, as cd on the ranges propated significant tox propared significant tox	supplier declarations, and /or analytical test data. Intentional ingredient in the semiconductor device and, to reason to believe that the unavoidable impurity concentratics. You can access the UL iQTM family of databases to olchloride (PVC) plastic. "Window envelopes" used to hold to stances restricted by RoHS in Microchip Technology Incorpided in Material Safety Data Sheets provided by raw material supplied by sew material supplied.	the best of Micro ation of the chemi btain a test report the packing slip o proprated's semice porated cannot gu rial suppliers. Suy	chip Technological substance, if at at on the outer box onductor device arantee the corpolier informatic provided only a	y f any, is not and certain s in their npleteness on is often as estimates		Total (mg) Doped Silicon	Total Chip (Die)2 7440-21-3 Total	100.00 % of Total Weight 100.00	1.58
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WEC (End-of-Life Vehicles (ELV) without exemption (zero) ance with the above EU Directives has been verified via intern mical substance is absent from the list above, the chemical substance is absent from the list above, the chemical substance is absent from the list above, the chemical substance is absent from the late of this document, the threshold of regulatory concern for any regulatory scheme grompounds used by Microchip meet the UL94 V0 flammabili Lcom/global/eng/pages/offerings/industries/chemicals/plastic otective "tubes" in which the specific product is shipped are not may be made from PVC plastic. Inip Technology Incorporated believes the information in this for packing materials is true and correct to the best of its knowled curacy of data in this form because it has been compiled based from disclosure as trade secrets and some information may average weight of these parts and the average weight of anticiplis contained within silicon devices (silicon IC) in the finished thip Technology Incorporated does not provide any warranty, end by Microchip Technology Incorporated and its subsidiaries cknowledgement, and invoices.	al design controls, substance is NOT an there is no credible world-wide. ty standard for plast standard form polyvinyl orm concerning subside and belief, as a do not the ranges propated significant tox parts.	upplier declarations, and /or analytical test data. Intentional ingredient in the semiconductor device and, to reason to believe that the unavoidable impurity concentratics. You can access the UL iQTM family of databases to old chloride (PVC) plastic. "Window envelopes" used to hold to stances restricted by RoHS in Microchip Technology Incorpided in Material Safety Data Sheets provided by raw material to the date issued in this form. Microchip Technology Incorpided in Material Safety Data Sheets provided by raw material to the supplier of the date is the date is the safety pata Sheets and raw material supplier is metals components. These estimates do not include train the respect to the information provided in this declaration prochip's standard terms and conditions of sale. These are eclarations and shall not be liable for any damages, direct	the best of Micro ation of the chemi btain a test report the packing slip o proprated's semice corrated cannot gu rial suppliers. Sup rial suppliers. Sup sice levels of dopan a. The exclusive, li e provided in Micr t or indirect, cons	chip Technological substance, is at at an the outer box conductor device arantee the corpoplier informatic provided only ants, metals, and mitted product to ochip's quotati equential or other substance.	y f any, is not and certain s in their rpleteness on is often as estimates non-metal warranties ons, sales nerwise,		Total (mg) Doped Silicon (mg) Total	Total Chip (Die)2 7440-21-3 Total Wire Bond1 7440-57-5	100.00 % of Total Weight 100.00 100.00 % of Total Weight 100.00	0.36
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SEC (End-of-Life Vehicles (ELV) without exemption (zero) ance with the above EU Directives has been verified via intern mical substance is absent from the list above, the chemical substance is absent from the list above, the chemical substance is absent from the list above, the chemical substance is absent from the date of this document, the threshold of regulatory concern for any regulatory scheme g compounds used by Microchip meet the UL94 V0 flammabili IL.com/global/eng/pages/offerings/industries/chemicals/plastic: obtective "tubes" in which the specific product is shipped are n may be made from PVC plastic. Thip Technology Incorporated believes the information in this f I packing materials is true and correct to the best of its knowle curacy of data in this form because it has been compiled base ed from disclosure as trade secrets and some information may average weight of these parts and the average weight of anticities contained within silicon devices (silicon IC) in the finished hip Technology Incorporated does not provide any warranty, ead by Microchip Technology Incorporated and its subsidiaries cknowledgement, and invoices. The disclaims any duty to notify users of updates or changes to d by users or third parties as a result of the users' reliance on ance for semiconductor products.	al design controls, substance is NOT an there is no credible world-wide. ty standard for plast standard for made from polyvinyl orm concerning subedge and belief, as conditioned to the tranges proported significant tox parts. The proposed significant tox parts.	supplier declarations, and /or analytical test data. Intentional ingredient in the semiconductor device and, to reason to believe that the unavoidable impurity concentratics. You can access the UL iQTM family of databases to old chloride (PVC) plastic. "Window envelopes" used to hold to stances restricted by RoHS in Microchip Technology Incorprided in Material Safety Data Sheets provided by raw material supplies in metals components. These estimates do not include traditionally incorprided in this form. Microchip Technology Incorprided by subcontract assemblers and raw material supplies in metals components. These estimates do not include tradition trochip's standard terms and conditions of sale. These are seclarations and shall not be liable for any damages, direct laterial Content Declarations (MCD) or independent third p	the best of Micro ation of the chemi btain a test report the packing slip o proprated's semice corrated cannot gu rial suppliers. Sup rial suppliers. Sup sice levels of dopan a. The exclusive, li e provided in Micr t or indirect, cons	chip Technological substance, is at at an the outer box conductor device arantee the corpoplier informatic provided only ants, metals, and mitted product to ochip's quotati equential or other substance.	y f any, is not and certain s in their rpleteness on is often as estimates non-metal warranties ons, sales nerwise,	0.07	Total (mg) Doped Silicon (mg) Total Doped Gold (mg) Total Doped Gold (mg) Total Palladium	Total Chip (Die)2 7440-21-3 Total Wire Bond1 7440-57-5 Total Wire Bond2 7440-57-5 Total Plating on external leads (pins) 7440-02-0 7440-05-3	100.00 % of Total Weight 90.00 5.00	0.36
3/EC (End-of-Life Vehicles (ELV) without exemption (zero) iance with the above EU Directives has been verified via intern emical substance is absent from the list above, the chemical substance is absent from the list above, the chemical substance is absent from the list above, the chemical substance is absent from the date of this document, the threshold of regulatory concern for any regulatory scheme ag compounds used by Microchip meet the UL94 V0 flammabili ul.com/global/eng/pages/offerings/industries/chemicals/plastic- otective "tubes" in which the specific product is shipped are n "may be made from PVC plastic. Thip Technology Incorporated believes the information in this f al packing materials is true and correct to the best of its knowle- curacy of data in this form because it has been compiled base- ted from disclosure as trade secrets and some information may average weight of these parts and the average weight of antici- plas contained within silicon devices (silicon IC) in the finished whip Technology Incorporated does not provide any warranty, e de by Microchip Technology Incorporated and its subsidiaries acknowledgement, and invoices. Thip disclaims any duty to notify users of updates or changes to d by users or third parties as a result of the users' reliance on iance for semiconductor products.	al design controls, substance is NOT an there is no credible world-wide. ty standard for plast standard for made from polyvinyl orm concerning subedge and belief, as conditioned to the tranges proported significant tox parts. The proposed significant tox parts.	supplier declarations, and /or analytical test data. Intentional ingredient in the semiconductor device and, to reason to believe that the unavoidable impurity concentratics. You can access the UL iQTM family of databases to old chloride (PVC) plastic. "Window envelopes" used to hold to stances restricted by RoHS in Microchip Technology Incorprided in Material Safety Data Sheets provided by raw material supplies in metals components. These estimates do not include traditionally incorprided in this form. Microchip Technology Incorprided by subcontract assemblers and raw material supplies in metals components. These estimates do not include tradition trochip's standard terms and conditions of sale. These are seclarations and shall not be liable for any damages, direct laterial Content Declarations (MCD) or independent third p	the best of Micro ation of the chemi btain a test report the packing slip o proprated's semice corrated cannot gu rial suppliers. Sup rial suppliers. Sup sice levels of dopan a. The exclusive, li e provided in Micr t or indirect, cons	chip Technological substance, is at at an the outer box conductor device arantee the corpoplier informatic provided only ants, metals, and mitted product to ochip's quotati equential or other substance.	y f any, is not and certain s in their rpleteness on is often as estimates non-metal warranties ons, sales nerwise,	0.07	Total (mg) Doped Silicon (mg) Total Doped Gold (mg) Total Doped Gold (mg) Total Nickel	Total Chip (Die)2 7440-21-3 Total Wire Bond1 7440-57-5 Total Wire Bond2 7440-57-5 Total Plating on external leads (pins) 7440-02-0	100.00 % of Total Weight 100.00 % of Total Weight 100.00 % of Total Weight 100.00 100.00 % of Total Weight 90.00	0.36

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